

Description

The SX5N10MI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 100V$ $I_D = 5A$

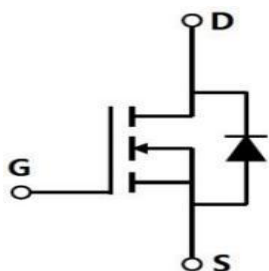
$R_{DS(ON)} < 125m\Omega$ @ $V_{GS}=10V$

Application

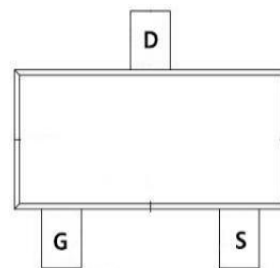
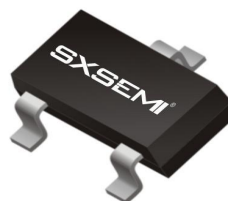
Battery protection

Load switch

Uninterruptible power supply



SOT-23-3L



Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	5	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.6	A
I_{DM}	Pulsed Drain Current ²	20	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ³	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-ambient(steady state) ¹	135	°C/W
	Thermal Resistance Junction-ambient($t < 10s$) ¹	85	°C/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	107	-	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
RDS(on)	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =10A	-	105	125	mΩ
		V _{GS} =4.5V, I _D =8A	-	125	135	mΩ
Ciss	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	610	-	pF
Coss	Output Capacitance		-	40	-	pF
Crss	Reverse Transfer Capacitance		-	25	-	pF
Qg	Total Gate Charge	V _{DS} =30V, I _D =10A, V _{GS} =10V	-	12	-	nC
Qgs	Gate-Source Charge		-	2.2	-	nC
Qgd	Gate-Drain("Miller") Charge		-	2.5	-	nC
td(on)	Turn-on Delay Time	V _{DS} =30V, I _D =5A, R _G =1.8Ω, V _{GS} =10V	-	7	-	ns
t _r	Turn-on Rise Time		-	5	-	ns
td(off)	Turn-off Delay Time		-	16	-	ns
t _f	Turn-off Fall Time		-	6	-	ns
IS	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	-	-	10	A
ISM	Pulsed Source Current ^{2,5}		-	-	40	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _S =10A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F =10A, dI/dt=100A/μs	-	21	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	21	-	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=11A
- 4.The power dissipation is limited by 150 °C junction temperature
- 5 .The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

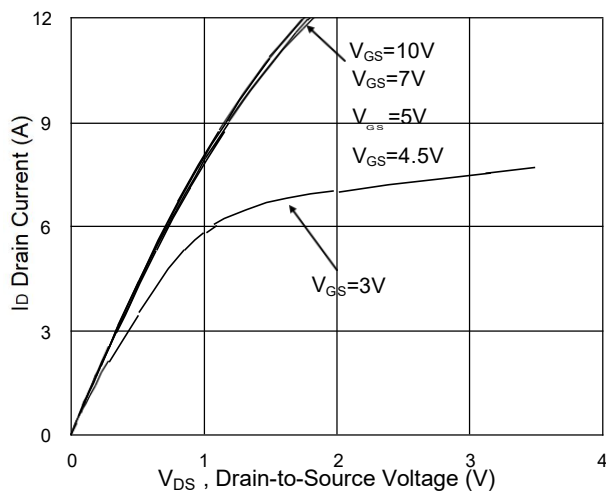


Fig.1 Typical Output Characteristics

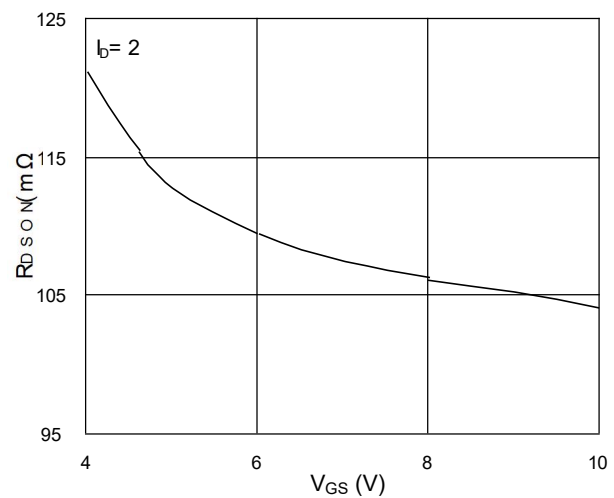


Fig.2 On-Resistance vs. Gate-Source

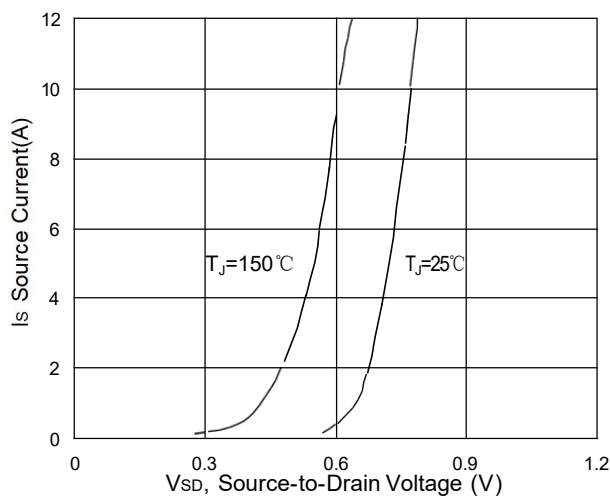


Fig.3 Forward Characteristics Of Reverse

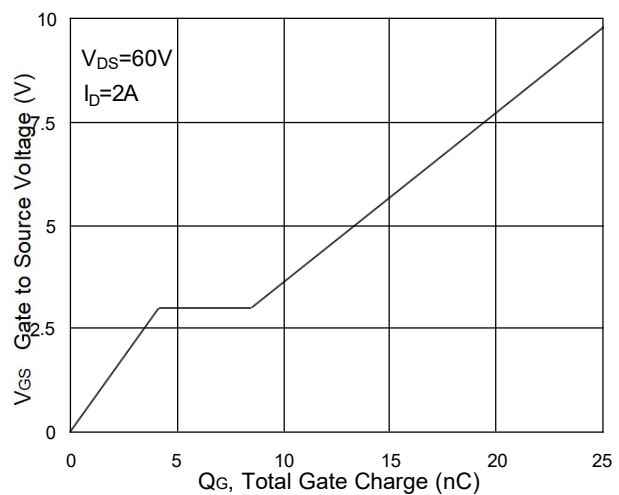


Fig.4 Gate-Charge Characteristics

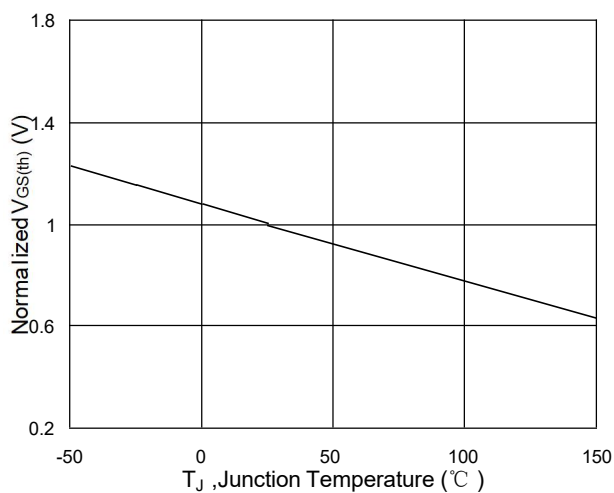


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

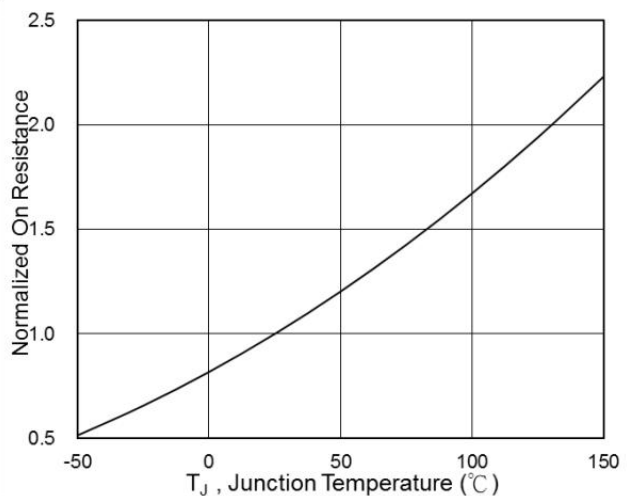
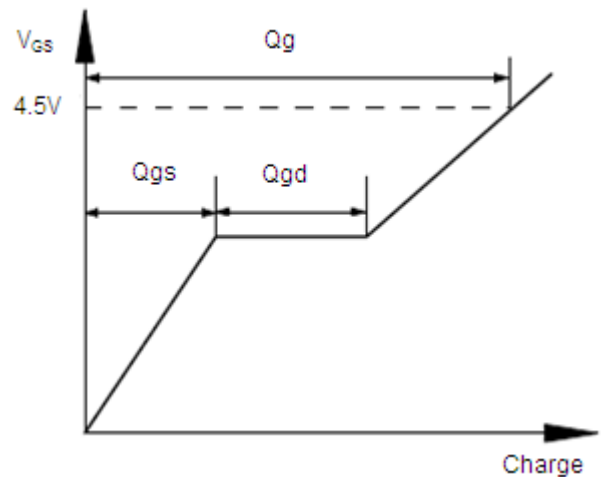
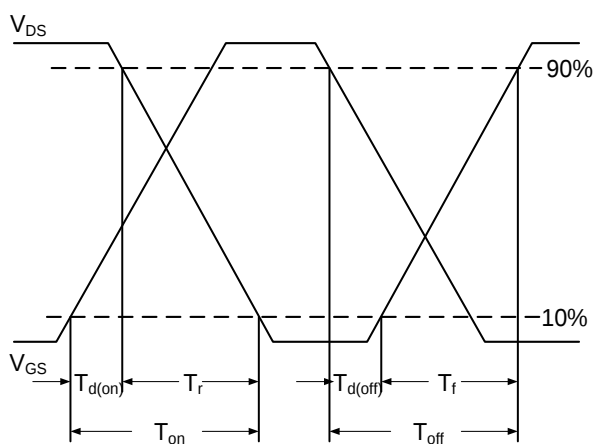
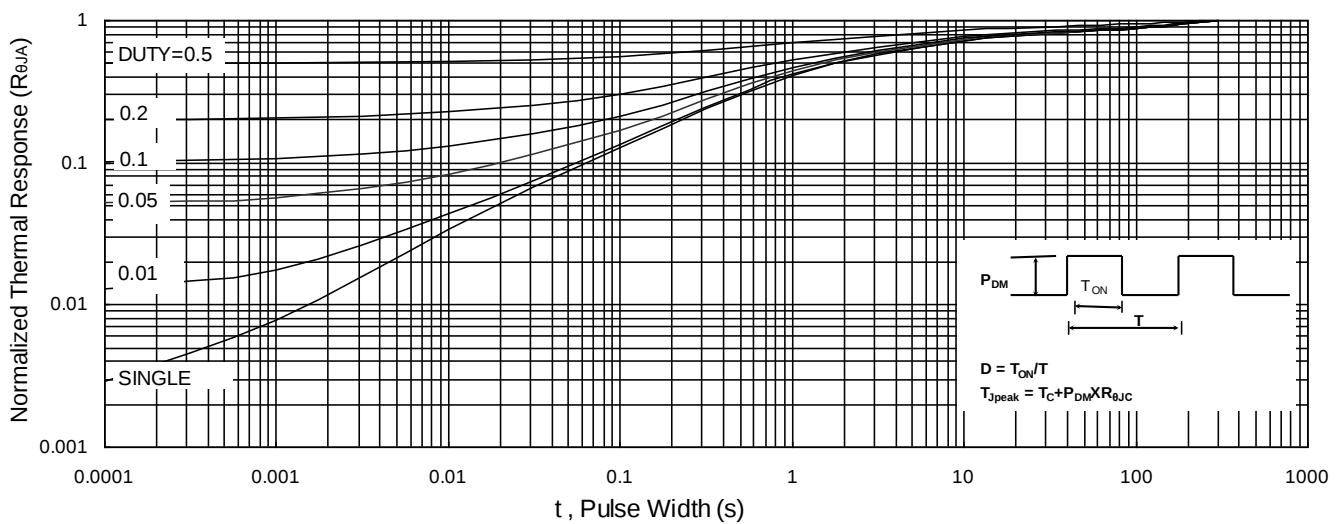
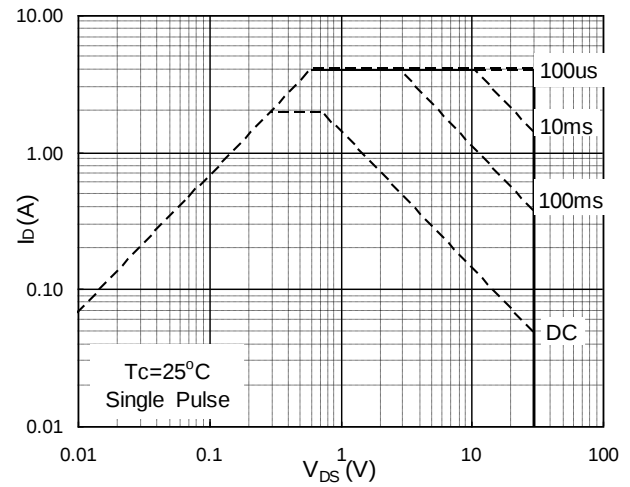
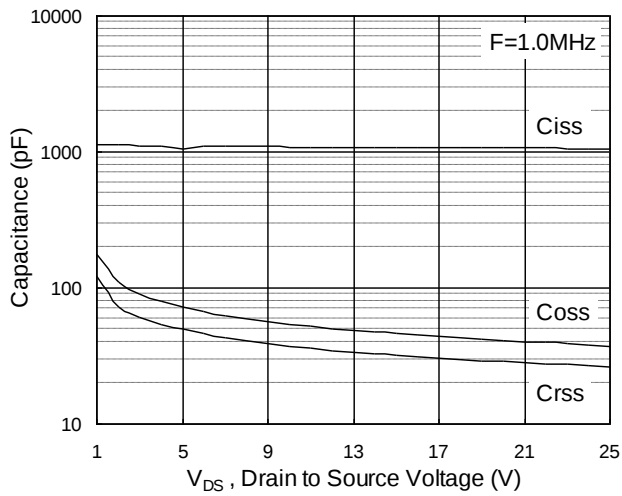
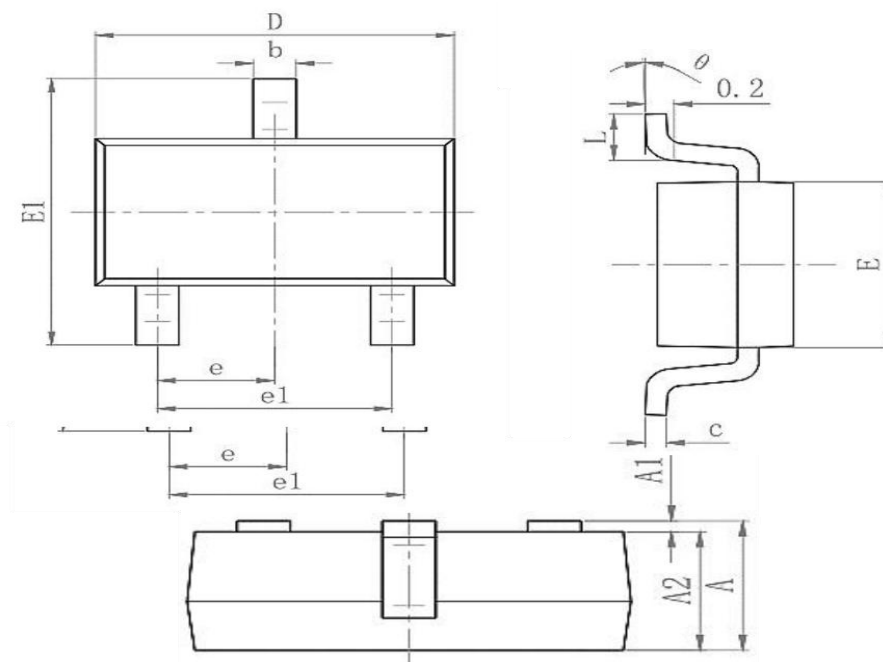


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Typical Characteristics



MOSFET Package Mechanical Data-SOT23-XC-Single



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.25	0.45
c	0.100	0.200
D	2.820	3.020
E	1.5	1.7
E1	2.650	2.950
e	0.950(BSC)	
e1	1.800	2.000
L	0.300	0.500
θ	0°	8°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOT-23-3L		3000